

# 0.9V Drive Nch MOSFET

**RYU002N05**

## ● Structure

Silicon N-channel MOSFET

## ● Features

- 1) High speed switing.
- 2) Small package(UMT3).
- 3) Ultra low voltage drive(0.9V drive).

## ● Application

Switching

## ● Packaging specifications

Type	Package	Taping
	Code	T306
	Basic ordering unit (pieces)	3000
RYU002N05		○

## ● Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

Parameter		Symbol	Limits	Unit
Drain-source voltage		$V_{DSS}$	50	V
Gate-source voltage		$V_{GSS}$	$\pm 8$	V
Drain current	Continuous	$I_D$	$\pm 200$	mA
	Pulsed	$I_{DP}$ *1	$\pm 800$	mA
Source current (Body Diode)	Continuous	$I_S$	150	mA
	Pulsed	$I_{SP}$ *1	800	mA
Power dissipation		$P_D$ *2	200	mW
Channel temperature		$T_{ch}$	150	$^\circ\text{C}$
Range of storage temperature		$T_{stg}$	-55 to +150	$^\circ\text{C}$

 \*1  $P_w \leq 10\mu\text{s}$ , Duty cycle  $\leq 1\%$ 

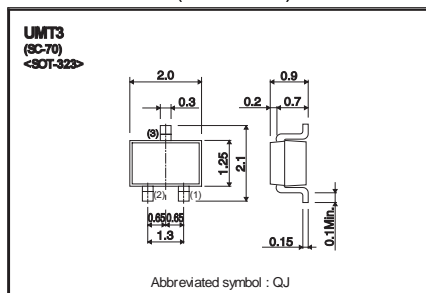
\*2 Each terminal mounted on a recommended land.

## ● Thermal resistance

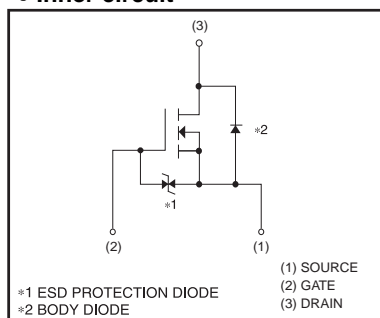
Parameter	Symbol	Limits	Unit
Channel to Ambient	$R_{th}(ch-a)^*$	625	$^\circ\text{C} / \text{W}$

\* Each terminal mounted on a recommended land.

## ● Dimensions (Unit : mm)



## ● Inner circuit



● Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	50	-	-	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	0.3	-	0.8	V	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> *	-	1.6	2.2	Ω	I <sub>D</sub> =200mA, V <sub>GS</sub> =4.5V
		-	1.7	2.4		I <sub>D</sub> =200mA, V <sub>GS</sub> =2.5V
		-	2.0	2.8		I <sub>D</sub> =200mA, V <sub>GS</sub> =1.5V
		-	2.2	3.3		I <sub>D</sub> =100mA, V <sub>GS</sub> =1.2V
		-	3.0	9.0		I <sub>D</sub> =10mA, V <sub>GS</sub> =0.9V
Forward transfer admittance	Y <sub>fs</sub>  *	0.2	-	-	S	I <sub>D</sub> =200mA, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	-	26	-	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	-	6	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	3	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	-	5	-	ns	I <sub>D</sub> =100mA, V <sub>DD</sub> =25V
Rise time	t <sub>r</sub> *	-	8	-	ns	V <sub>GS</sub> =4.5V
Turn-off delay time	t <sub>d(off)</sub> *	-	17	-	ns	R <sub>L</sub> =250Ω
Fall time	t <sub>f</sub> *	-	43	-	ns	R <sub>G</sub> =10Ω

\*Pulsed

● Body diode characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	1.2	V	I <sub>s</sub> =200mA, V <sub>GS</sub> =0V

\*Pulsed

● Electrical characteristics curves

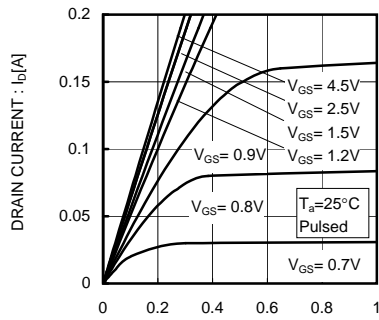


Fig.1 Typical Output Characteristics( I )

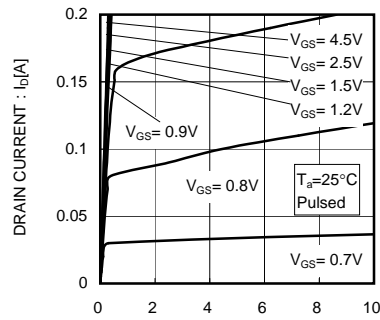


Fig.2 Typical Output Characteristics( II )

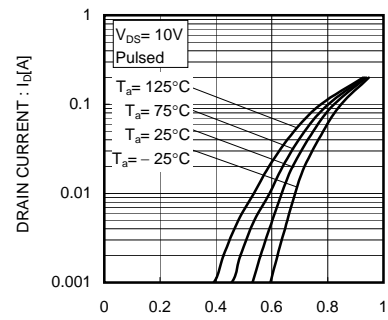


Fig.3 Typical Transfer Characteristics

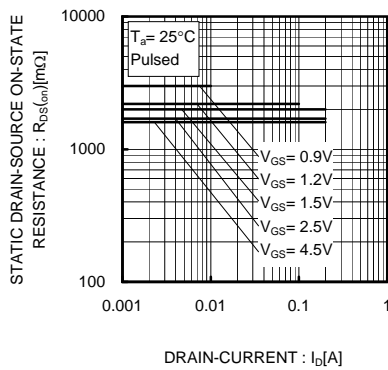


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

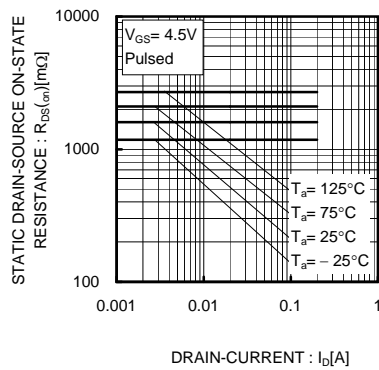


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

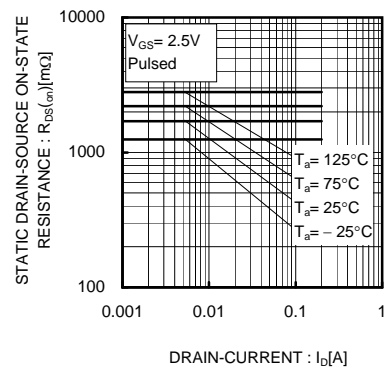


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )

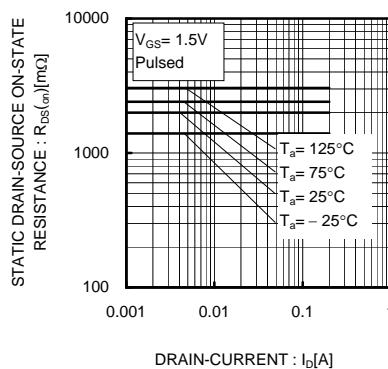


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current( IV )

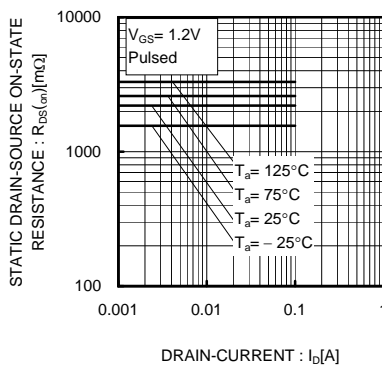


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current( V )

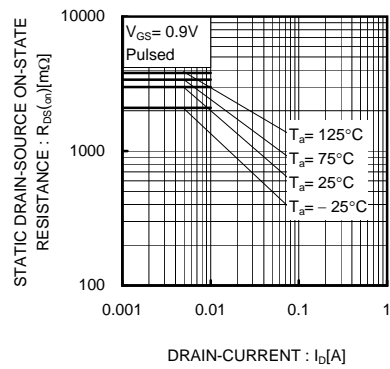


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current( VI )

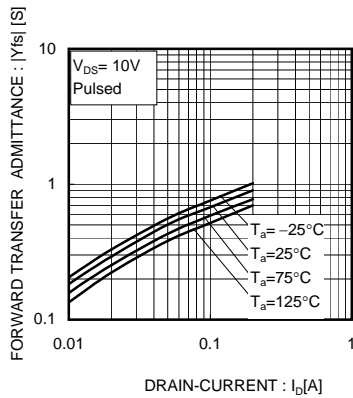


Fig.10 Forward Transfer Admittance vs. Drain Current

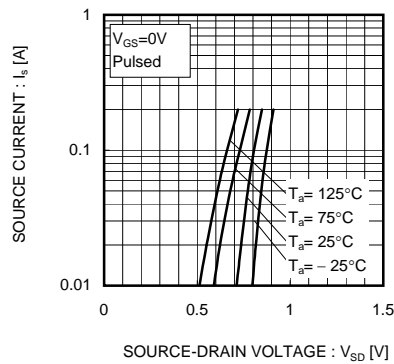


Fig.11 Reverse Drain Current vs. Source-Drain Voltage

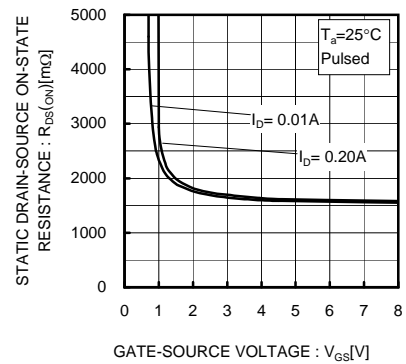


Fig.12 Static Drain-Source On-State Resistance vs. Gate Source Voltage

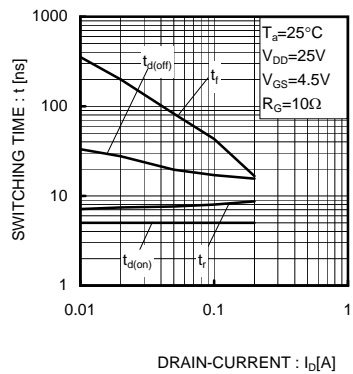


Fig.13 Switching Characteristics

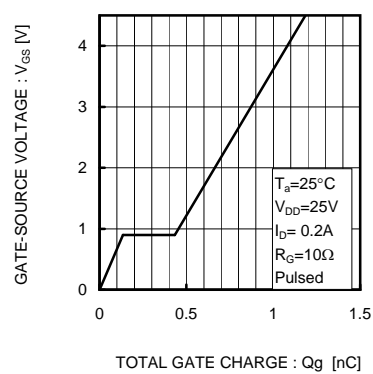


Fig.14 Typical Capacitance vs. Drain-Source Voltage

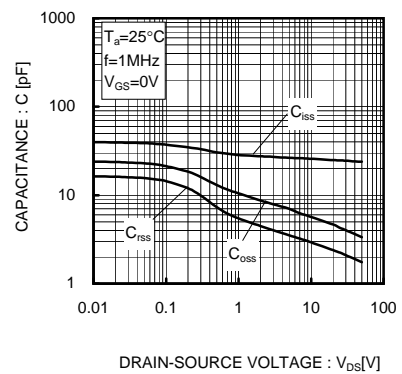


Fig.15 Typical Capacitance vs. Drain-Source Voltage

# ● Measurement circuits

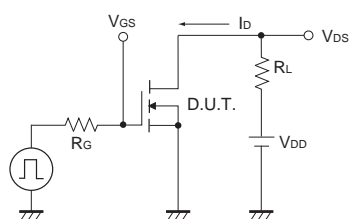


Fig.1-1 Switching Time Measurement Circuit

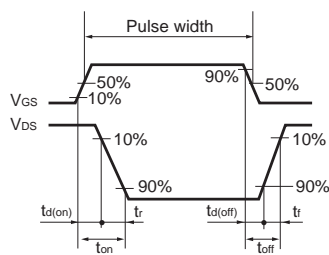


Fig.1-2 Switching Waveforms

# ● Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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